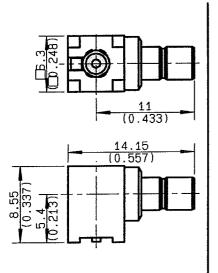
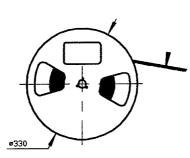
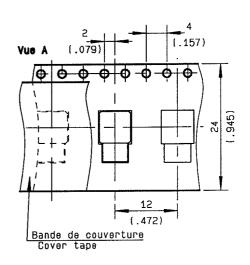
FOR PCB SMT TYPE REEL OF 100

R114.664.100

Series: SMB







All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BRASS BRASS - PTFE	GOLD 0.2 OVER NICKEL 2 GOLD 0.5 OVER NICKEL 2

Issue: 0427 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



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PACKAGING

Standard	Unit	Other
100	•	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance $\mathbf{50} \ \Omega$ Frequency $\mathbf{0-4} \ \mathrm{GHz}$

Frequency **0-4** GHz VSWR **1.2** + **0.000** x F(GHz) Maxi

Insertion loss $NA \sqrt{F(GHz)} dB Maxi$ RF leakage - (NA - F(GHz)) dB Maxi

Voltage rating 335 Veff Maxi Dielectric withstanding voltage Insulation resistance 1000 Veff mini 1000 M Ω mini

ENVIRONMENTAL

Operating temperature -65/+165 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

10 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 500 Cycles mini

Weight **2.640** g

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SOLDER PROCEDURE

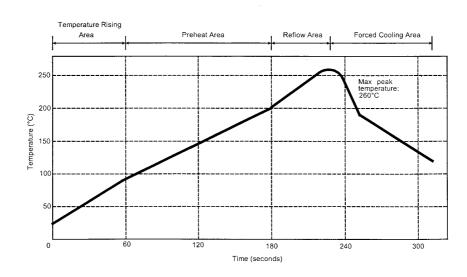
1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

We advise a thickness of 200 microns (7.800 microinch).

Verify that the edges of the zone are clean.

- 2. Placement of the receptacle on the mounting zone. Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards by CFC solvents (or a substitute product according the United Nation's environmental programm)
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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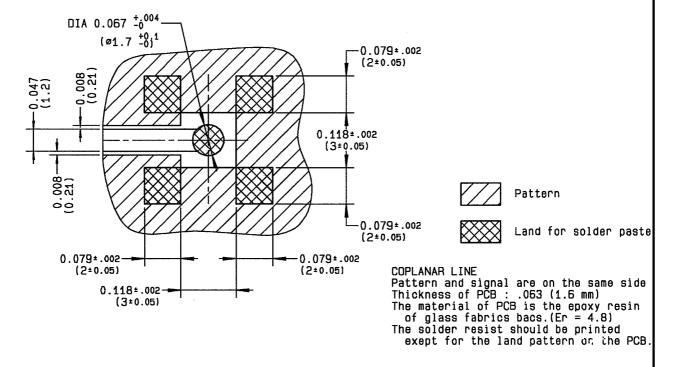


FOR PCB SMT TYPE REEL OF 100

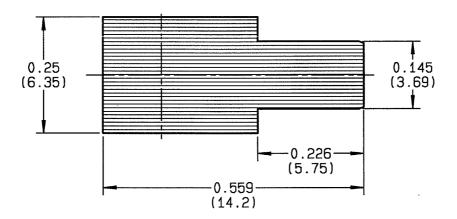
R114.664.100

Series: SMB

SMB SERIES - INFORMATIONS



SHADOW OF SMB RECEPTACLE FOR VIDEO CAMERA



Issue : 0427 A

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